

WHAT IS CLAIMED IS

1     1.         An electronic device comprising:  
2                 a sealed housing;  
3                 an electrical circuit component in said sealed  
4     housing; and  
5                 a movable fin that protrudes to the outside of  
6     said sealed housing depending on a rise in internal  
7     temperature of said sealed housing.

1     2.         An electronic device as claimed in claim 1,  
2     wherein said movable fin protrudes to the outside of said  
3     sealed housing through a guide hole formed in said sealed  
4     housing, and has airtightness means between itself and said  
5     guide hole.

1     3.         An electronic device as claimed in claim 1,  
2     wherein a heat generating portion of a package or the like  
3     mounted therein with said electrical circuit component and  
4     said movable fin are connected to each other by a flexible  
5     sheet.

1     4.         An electronic device as claimed in claim 2,  
2     wherein a heat generating portion of a package or the like  
3     mounted therein with said electrical circuit component and  
4     said movable fin are connected to each other by a flexible  
5     sheet.

1 5. An electronic device as claimed in claim 1,  
2 wherein said movable fin is caused to protrude to the  
3 outside of said sealed housing by a member that returns to  
4 its original shape at a set temperature.

1 6. An electronic device as claimed in claim 2,  
2 wherein said movable fin is caused to protrude to the  
3 outside of said sealed housing by a member that returns to  
4 its original shape at a set temperature.

1 7. An electronic device as claimed in claim 3,  
2 wherein said movable fin is caused to protrude to the  
3 outside of said sealed housing by a member that returns to  
4 its original shape at a set temperature.

1 8. An electronic device as claimed in claim 4,  
2 wherein said movable fin is caused to protrude to the  
3 outside of said sealed housing by a member that returns to  
4 its original shape at a set temperature.

1 9. An electronic device comprising:  
2 a sealed housing;  
3 an electrical circuit component in said sealed  
4 housing; and  
5 a bellows container with a variable internal  
6 volume that is connected between a first hole in an upper

7 part of said sealed housing and a second hole in a lower  
8 part thereof.

1 10. An electronic device comprising:  
2 a sealed housing;  
3 an electrical circuit component in said sealed  
4 housing; and  
5 an expandable/contractible balloon that is  
6 connected between a first hole in an upper part of said  
7 sealed housing and a second hole in a lower part thereof.

1 11. A heat radiation method for an electronic device  
2 having a sealed housing, wherein, when an internal  
3 temperature of said sealed housing having therein an  
4 electrical circuit component rises, a movable fin is caused  
5 to protrude to the outside of said sealed housing.

1 12. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 11, wherein  
3 said movable fin is caused to protrude through a guide hole  
4 formed in said sealed housing, while keeping airtightness.

1 13. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 11, wherein  
3 heat of a package or the like mounted therein with said  
4 electrical circuit component is conducted to said movable  
5 fin by a flexible sheet.

1 14. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 12, wherein  
3 heat of a package or the like mounted therein with said  
4 electrical circuit component is conducted to said movable  
5 fin by a flexible sheet.

1 15. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 11, wherein  
3 said movable fin is caused to protrude by deformation of a  
4 member due to a temperature, said member adapted to return  
5 to its original shape.

1 16. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 12, wherein  
3 said movable fin is caused to protrude by deformation of a  
4 member due to a temperature, said member adapted to return  
5 to its original shape.

1 17. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 13, wherein  
3 said movable fin is caused to protrude by deformation of a  
4 member due to a temperature, said member adapted to return  
5 to its original shape.

1 18. A heat radiation method for an electronic device  
2 having a sealed housing as claimed in claim 14, wherein

3 said movable fin is caused to protrude by deformation of a  
4 member due to a temperature, said member adapted to return  
5 to its original shape.

1 19. A heat radiation method for an electronic device  
2 having a sealed housing, wherein, when an internal  
3 temperature of said sealed housing having therein an  
4 electrical circuit component rises, a bellows container  
5 connected between a first hole in an upper part of said  
6 sealed housing and a second hole in a lower part thereof  
7 increases its internal volume.

1 20. A heat radiation method for an electronic device  
2 having a sealed housing, wherein, when an internal  
3 temperature of said sealed housing having therein an  
4 electrical circuit component rises, an  
5 expandable/contractible balloon connected between a first  
6 hole in an upper part of said sealed housing and a second  
7 hole in a lower part thereof increases its internal volume.

1 21. A sealed housing of an electronic device,  
2 comprising:  
3 a guide hole; and  
4 a movable fin that protrudes to the outside  
5 through said guide hole depending on a rise in internal  
6 temperature of said sealed housing.

1 22. A sealed housing of an electronic device as  
2 claimed in claim 21, wherein said movable fin has  
3 airtightness means between itself and said guide hole.

1 23. A sealed housing of an electronic device as  
2 claimed in claim 21, further comprising a flexible sheet  
3 connecting between a heat generating portion mounted in  
4 said sealed housing and said movable fin.

1 24. A sealed housing of an electronic device as  
2 claimed in claim 22, further comprising a flexible sheet  
3 connecting between a heat generating portion mounted in  
4 said sealed housing and said movable fin.

1 25. A sealed housing of an electronic device as  
2 claimed in claim 21, wherein said movable fin is caused to  
3 protrude to the outside by a member that returns to its  
4 original shape at a set temperature.

1 26. A sealed housing of an electronic device as  
2 claimed in claim 22, wherein said movable fin is caused to  
3 protrude to the outside by a member that returns to its  
4 original shape at a set temperature.

1 27. A sealed housing of an electronic device as  
2 claimed in claim 23, wherein said movable fin is caused to  
3 protrude to the outside by a member that returns to its

4 original shape at a set temperature.

1 28. A sealed housing of an electronic device as  
2 claimed in claim 24, wherein said movable fin is caused to  
3 protrude to the outside by a member that returns to its  
4 original shape at a set temperature.

1 29. A sealed housing of an electronic device,  
2 comprising:  
3 a first hole in an upper part of said sealed  
4 housing;  
5 a second hole in a lower part of said sealed  
6 housing; and  
7 a bellows container with a variable internal  
8 volume that is connected between said first hole and said  
9 second hole.

1 30. A sealed housing of an electronic device,  
2 comprising:  
3 a first hole in an upper part of said sealed  
4 housing;  
5 a second hole in a lower part of said sealed  
6 housing; and  
7 an expandable/contractible balloon that is  
8 connected between said first hole and said second hole.